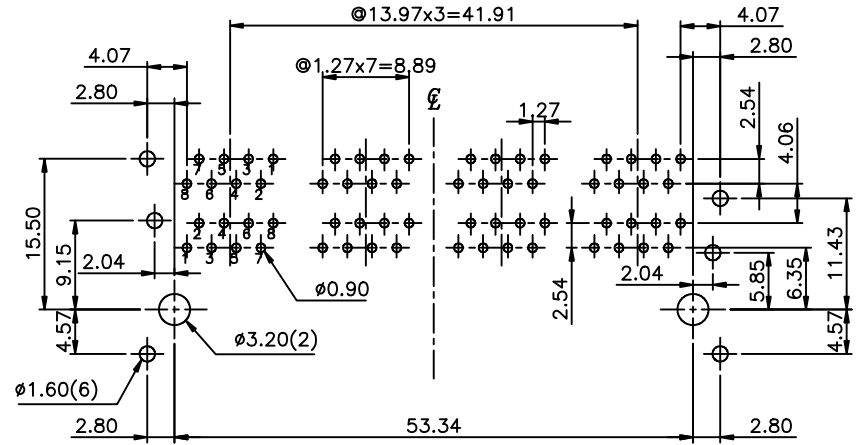
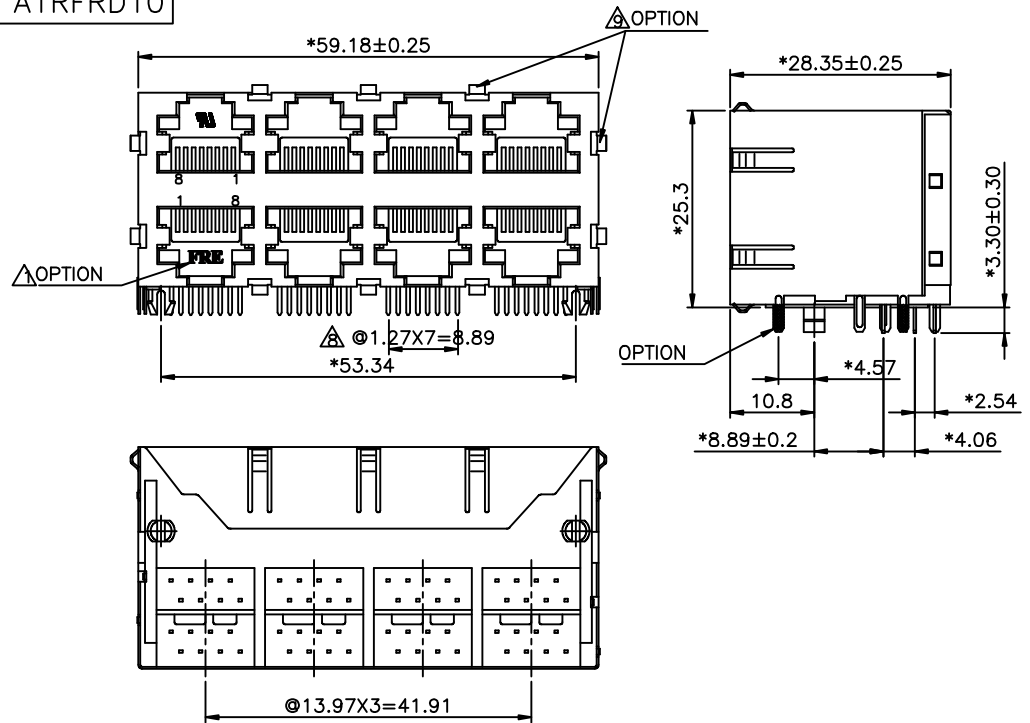


A1RFRD10

		MODIFY PART NO.	QJULER 01/28/05	REVISION RECORD				
		ADD OPTION	YAN 06/17/05	REV	ECO	DESCRIPTION	DRFT	CHKD
△				△		ADD OPTION	Ming-Wei 04/06/02	
△				△		ADD OPTION	Syng 7/24/03	
△				△		ADD OPTION	Syng 11/4/03	
△				△		ADD PART NO.	Changpu 4/17/04	
△				△		ADD PART NO.	Changpu 10/29/04	
△				△		MODIFY PART NO.	LIUXIN 11/10/04	
△				△		MODIFY PART NO.	YAN 12/16/04	



PC Board Layout Component Side Shown
Thickness=1.6mm

NOTES:

ELECTRICAL:

- VOLTAGE RATING : 125 VAC RMS.
- CURRENT RATING : 1.5 AMP.
- CONTACT RESISTANCE : 50 MILLIOHMS MAX.
- INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
- DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

- HOUSING & INSERT MATERIAL : GLASS FILLED POLYESTER UL94V-0.
- CONTACT MATERIAL : PHOSPHOR BRONZE, t=0.35mm.
- SHIELD MATERIAL : COPPER ALLOY, t=0.25mm.
- PLATING : GOLD PLATING OVER NICKEL.
- OPERATING LIFE : 750 CYCLES MIN.
- PCB RETENTION PRE-SOLDER : 1 LB MIN.
- PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

- STORAGE : -40°C TO +85°C.
- OPERATION: -40°C TO +85°C.

MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68, SUBPART F.
CUL FILE NO. E163191

PART NUMBER: E5908-XXC1XX

- △2-W/ TOP TABS
- △3-W/ SIDE TABS
- △4-W/ TOP&SIDE TABS
- 5-W/ TOP&BOTTOM&SIDE TABS
- 1- 3u" 2- 6u" 3-15u"
- 4-30u" 5-50u" F-GOLD FLASH △
- 4- W/FRE LOGO
- U- W/O FRE LOGO
- T- Tin
- V- Nickel
- J- W/NICKEL PLATED WITH TINNED GROUNDING PEG
- △Q- GOLD

DETACHED LISTS	MM (INCH)		DFTO Ming-Wei	DATE 03/20/2002	FULL RISE ELECTRONIC CO., LTD	
	TOLERANCES EXCEPT AS NOTED		CHKD	DATE		
	MM	±	MFO	DATE	TITLE STAMPED PIN III STACKED GANGED JACK, 2X4	
	.0 ± 0.2	±	APPLV XLF	DATE 06/24/05		
.00 ± 0.15	±	MATERIAL :		DRAWING NO. GE593B51		
.000 ± 0.075	±	ANGLES ± 0.5		/PART NO. SEE NOTE		
THIRD ANGLE PROJECTION		QT'Y :		SIZE REV		
		FINISH :		A3 9		
		SCALE : 1.5 : 1		DO NOT SCALE DRAWING		
				SHEET 1 OF 1		